

L Number	Hits	Search Text	DB	Time stamp
1	645	hybrid adj electronic	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:14
2	1304	pouring adj resin	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:14
3	14846	harden\$3 adj resin	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:15
4	1866	pour\$3 adj resin	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:16
5	4148	cut\$4 adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:16
6	110288	electronic adj device	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:17
7	0	(electronic adj device) and (pour\$3 adj resin) and (harden\$3 adj resin) and (cut\$4 adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:17
8	8	(electronic adj device) and (pour\$3 adj resin) and (harden\$3 adj resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:22
9	4	("4364017" "4734608" "5010270" "5243250").PN.	USPAT	2004/10/17 13:20
10	4	("4364017" "4734608" "5010270" "5243250").PN.	USPAT	2004/10/17 13:20
11	25	(electronic adj device) and (pour\$3 adj resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:22
12	184128	hardening	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:23
13	11	((electronic adj device) and (pour\$3 adj resin)) and hardening	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:23
14	850789	cutting	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:23
15	5	((electronic adj device) and (pour\$3 adj resin)) and hardening) and cutting	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:32
16	25	(electronic adj device) and (pour\$3 adj resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:32
17	1284	individual adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:34
18	82068	electronic adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:34

19	27	(electronic adj circuit) and (harden\$3 adj resin) and cutting	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:35
21	43592	gluing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:35
22	1	gluing and (((electronic adj circuit) and (harden\$3 adj resin) and cutting) and hardening)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:35
20	24	((electronic adj circuit) and (harden\$3 adj resin) and cutting) and hardening	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:40
23	127545	pouring	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:40
24	1	(((electronic adj circuit) and (harden\$3 adj resin) and cutting) and hardening) and pouring	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:40
25	13315	liquid adj resin	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:41
26	0	(((electronic adj circuit) and (harden\$3 adj resin) and cutting) and hardening) and (liquid adj resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:40
27	1	(liquid adj resin) and hardening and cutting and (electronic adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:41
28	17	(liquid adj resin) and hardening and (electronic adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:43
29	1	(liquid adj resin) and hardening and (electronic adj circuit) and cutting	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:54
30	43592	gluing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:54
31	0	((liquid adj resin) and hardening and (electronic adj circuit)) and gluing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/17 13:54